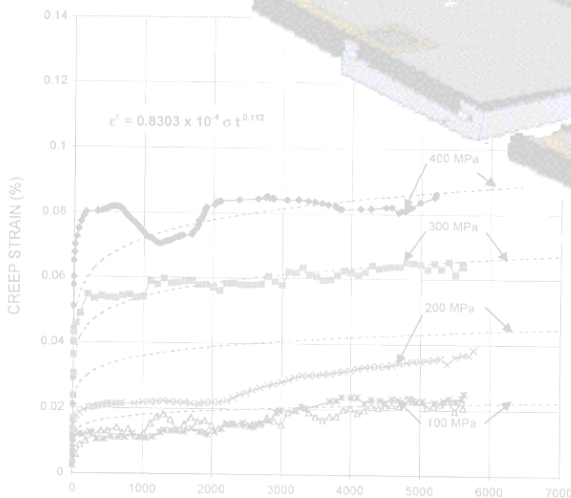


# Low-Mass Layer 0 Support Ideas

for **SuperB** Silicon

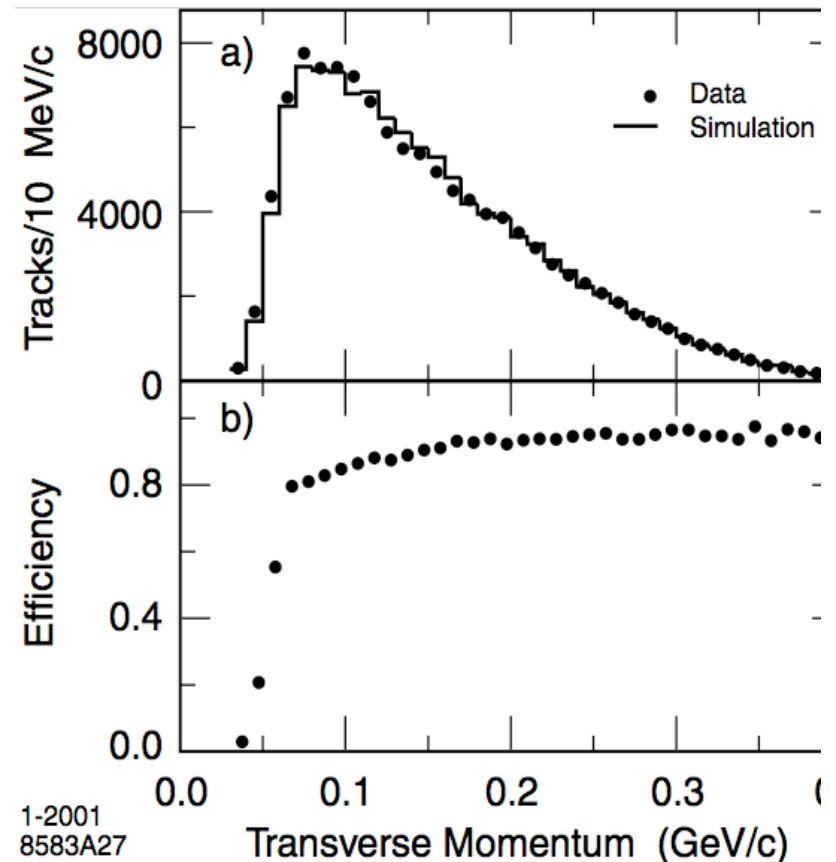


J. Albert  
Apr. 26, 2006

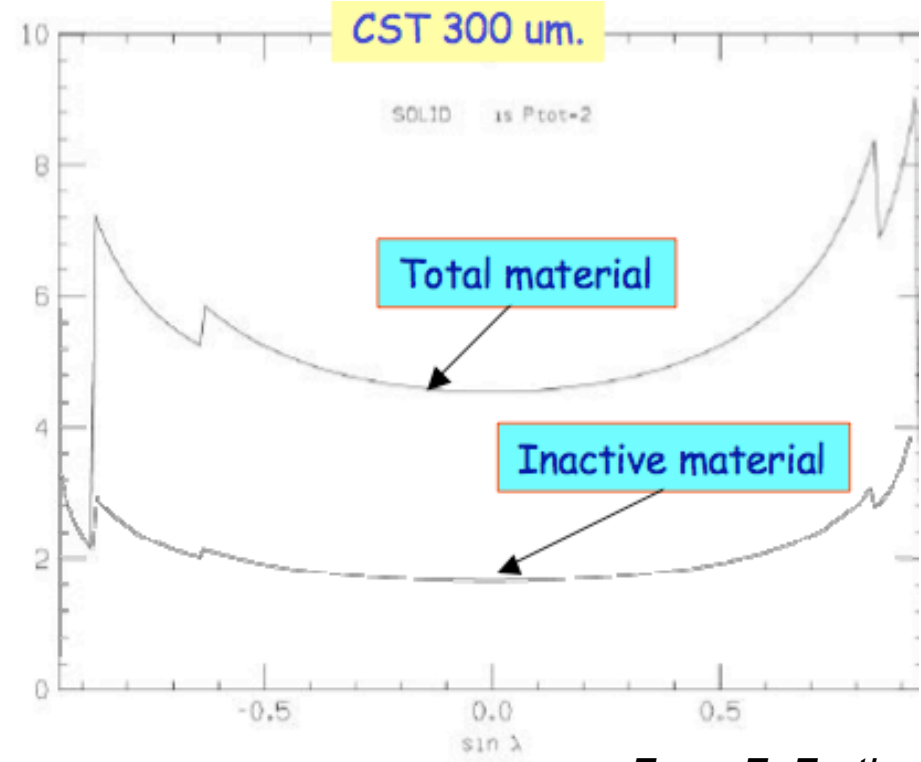
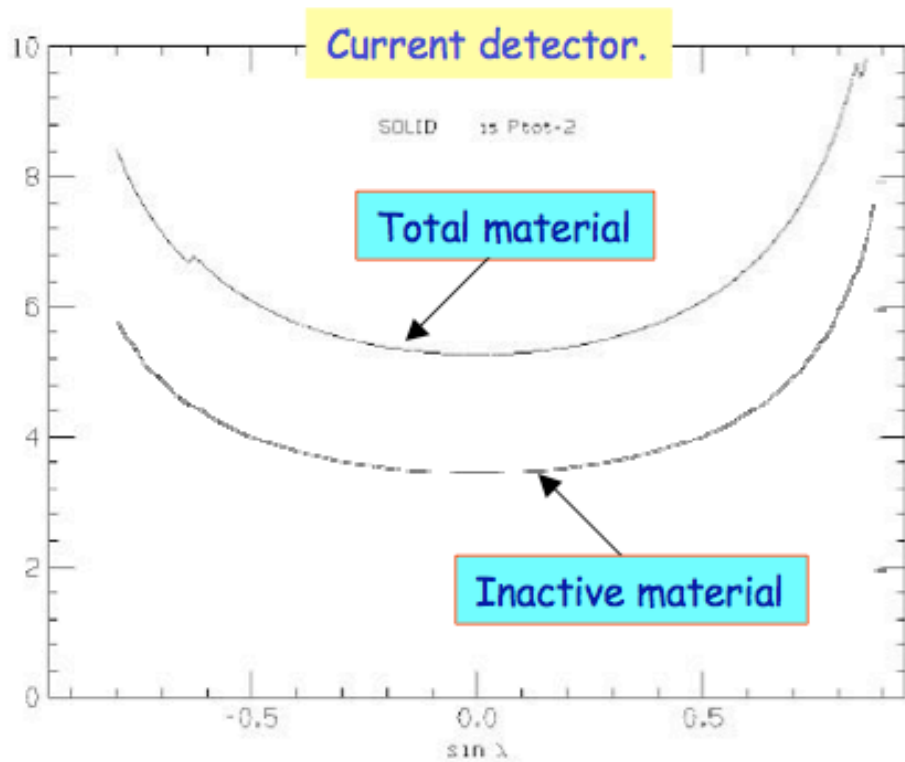
UK SuperB Meeting Apr. 26-27, 2006  
Daresbury Laboratory

# Overview

- ❑ A large fraction of SuperB physics will involve some slow tracks (e.g. Breco sample, hadronic tag analyses using  $D^*$ , etc.)
- ❑ Even small amounts of multiple scattering worsens slow pion (and other slow track) **efficiency**, **acceptance**,  $\Delta m$  resolution. This is primarily an issue for the innermost layers (& beampipe).
- Make sure layer 0 has as little material as possible! (Without sacrificing resolution, increasing noise...!)
- How? One way is to use a **carbon fiber filament-based tension support structure**.



# Material Budget



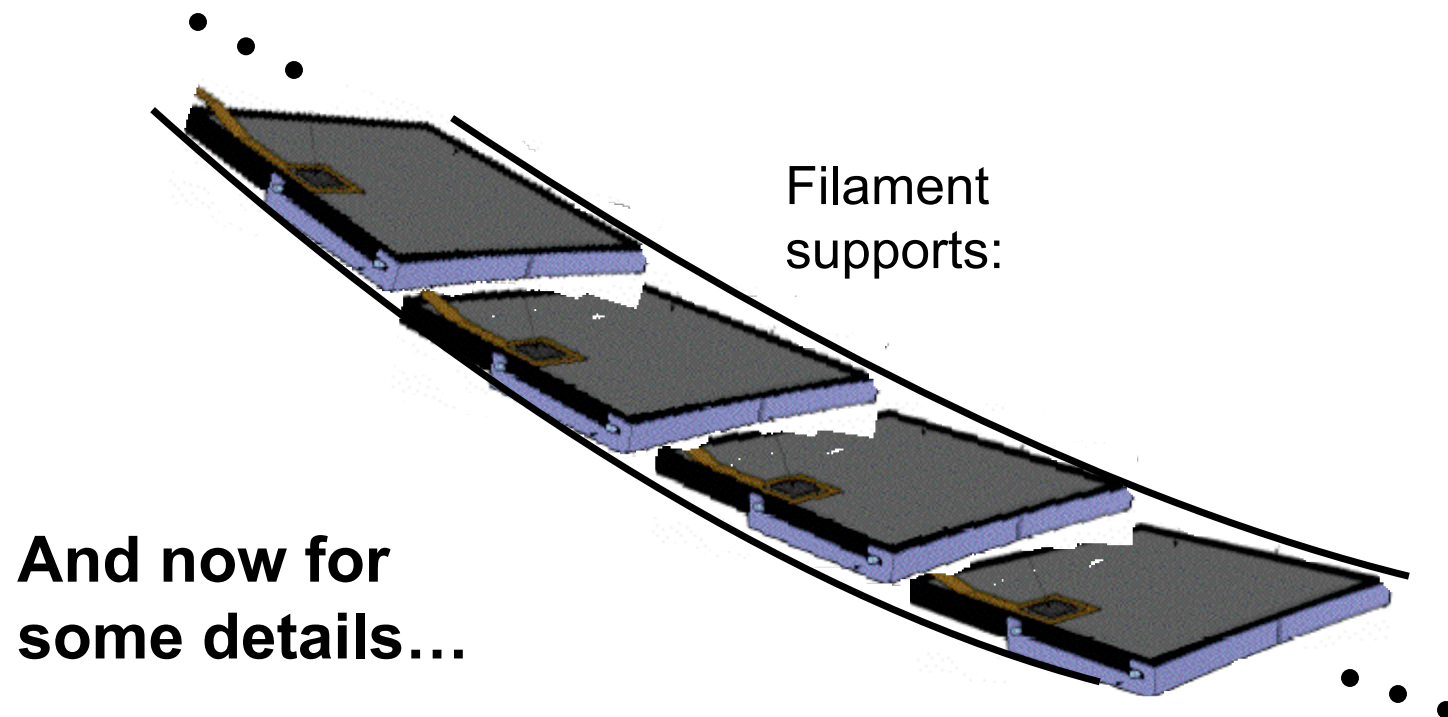
From F. Forti

- Inactive material dominates, unless support tube is removed.
- Even if support tube is removed, if layer 0 uses **thinner than 300 um silicon** (likely), then inactive material will *vastly* dominate that layer if a similar support structure to the present rigid frame is used there.

# Basic Concept

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- Place modules between thin carbon fiber filaments.
- Filaments, under tension, support the modules.
- Services & readout supported, alongside the modules, by the filaments.
- Vastly reduces support structure.
- Filaments easily oriented for appropriate Lorentz angle.





# Filaments

- Carbon fiber provides very high yield strength, low creep with low mass / Z.
- Optimization of filament properties:
  - Sag must not increase over time.
  - Sag must be “small”...
  - **Must be calibratable at all points *and times* to  $\ll 10$  um (approximate resolution).**
  - Must have safety factor for creep (above), C.F. yield strength (obviously).
  - Must have safety factor for major shaking / earth movement.
  - Vibration properties must be both small and fully calibratable.

## **Carbon Fiber General Properties**

**Yield strength:**  $6.9 \times 10^8$  Pa

**Young's modulus:**  $2.4 \times 10^{11}$  Pa

**Density:**  $1.8 \times 10^3$  kg m<sup>-3</sup>

**Thermal C.E.:**  $1-3 \times 10^{-6}$  K<sup>-1</sup> (match Si)

**Specific heat:**  $7.1 \times 10^2$  J kg<sup>-1</sup> K<sup>-1</sup>

**Material:** 0-90° crossply C.F. matrix

**Width:** 2 mm

**Thickness:** 250 um

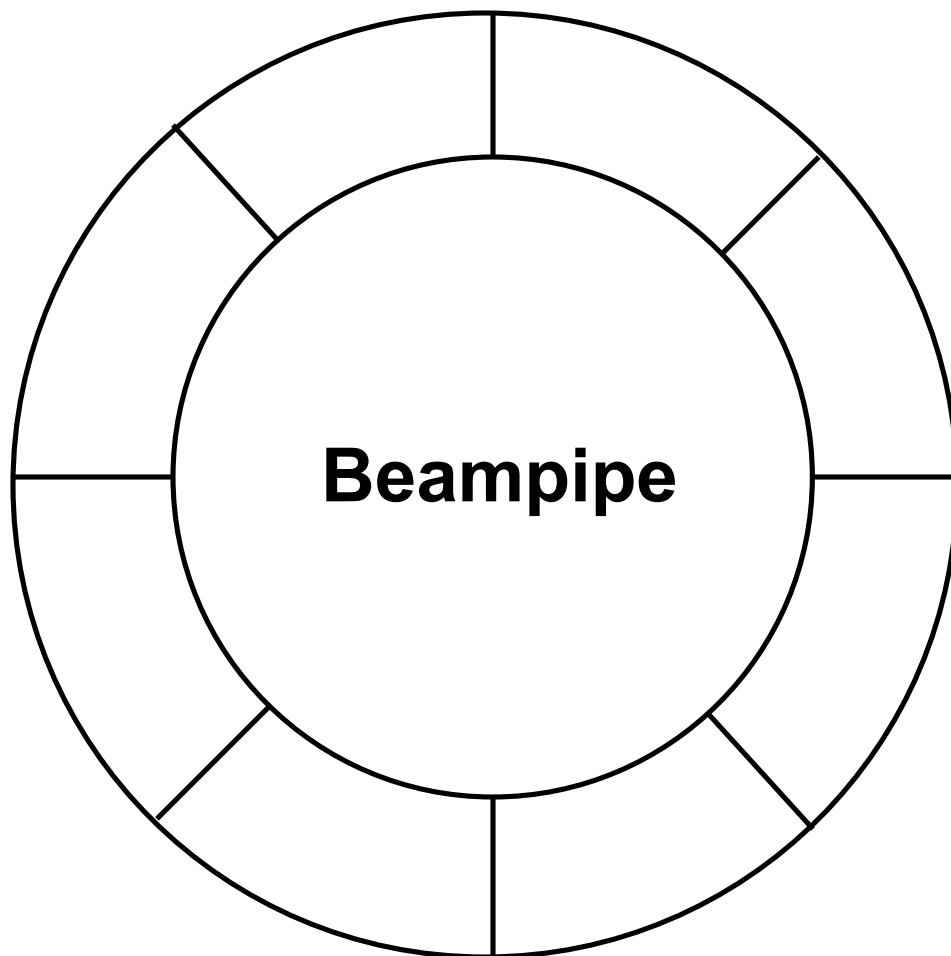
**Tension:** 5 N (=  $1 \times 10^7$  Pa)

**Mass (incl. modules):** 0.19 kg (L5)

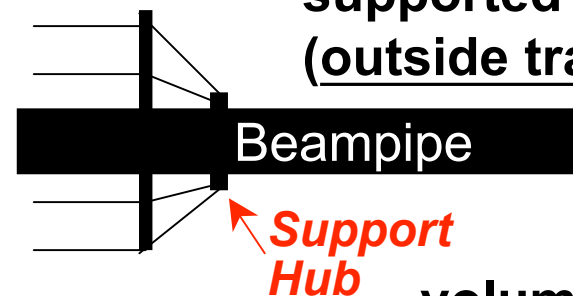
**Sagitta:** 6.9 mm (L5 = max)

# End Supports

- End supports must also be low mass, but able to hold tension of support filaments.
- Use old idea from Al Odian (SLAC – & others): “*bicycle-wheel*”:



**Material:** C.F. rims, spokes  
**Width:** *Not yet determined*  
**Thickness:** *Not yet determined*  
**Mass:** *Not yet determined*



**Majority of tension supported by hub (outside tracking**

**Beampipe**

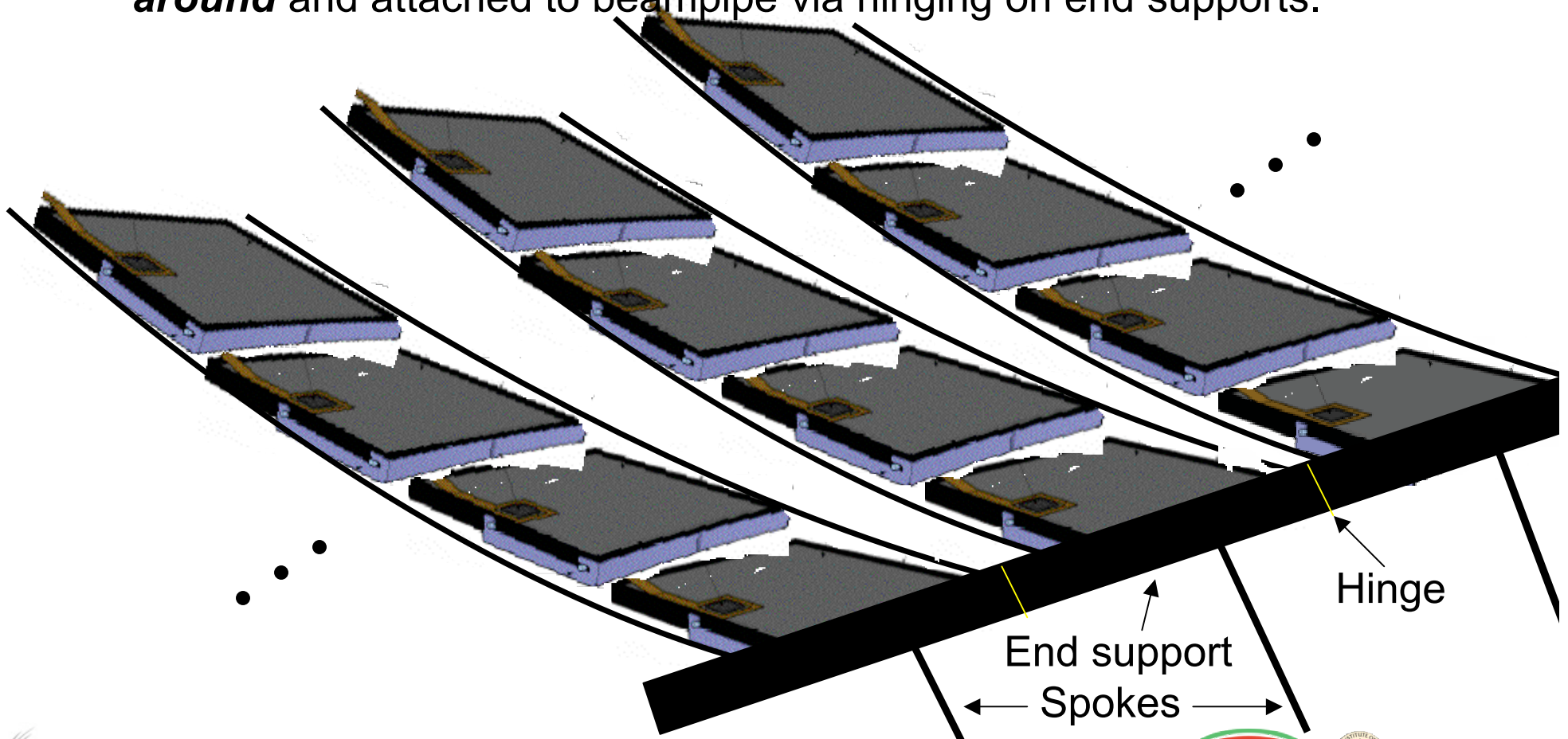
**Support Hub**

**volume) so support rims do not need to hold off much tension!**

*But FEA study needed to really determine appropriate dimensions...*

# Assembly

- Assembly could be done more simply by having a hinged end support.
- Module insertion onto filament frame structure done **flat** on a filament frame stand. (Also good for cosmic tests.)
- Then, on final assembly, layer 0 (very carefully, mechanically) **wrapped around** and attached to beampipe via hinging on end supports.



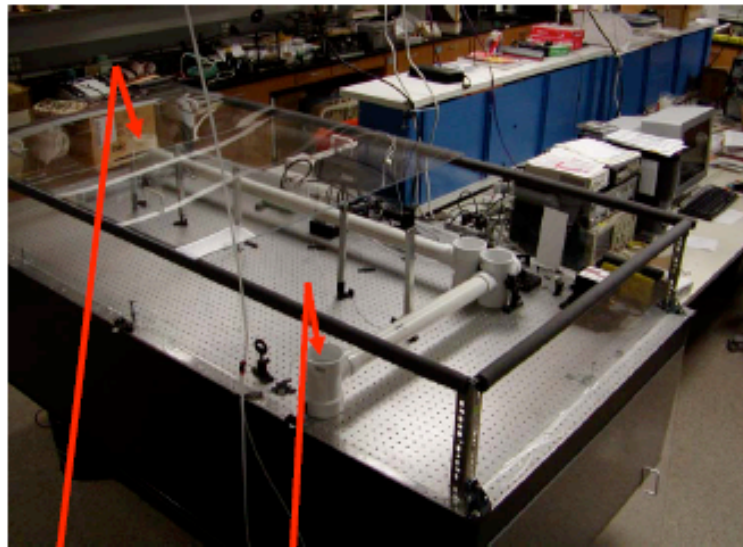
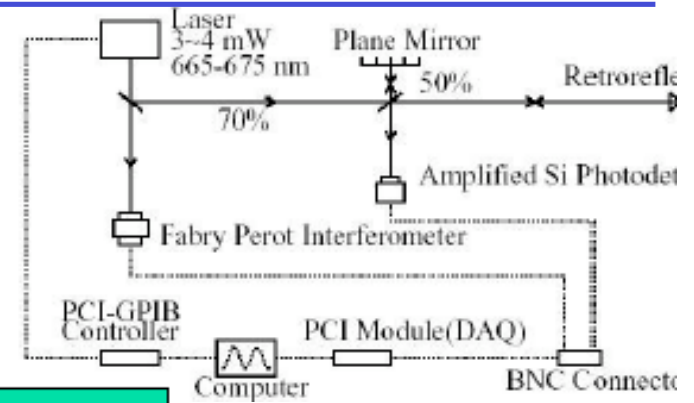
# Deflections / Alignment

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- The filaments will nominally take the shape of an “elastic catenary,” a function that’s well-known from structural engineering in cable structures.
- However, very clearly each module will require exact calibration of its position and Euler angles, to provide a proper bootstrap point for track-based calibration.
- Furthermore, a highly precise position calibration must be done **in real time**, due to vibrations from microphonics, etc. (Particle tracks will be largely unhelpful for such a real-time calibration.)
- Fortunately, technology for real-time calibration for position of individual silicon modules is being developed and largely available...

# FSI Alignment (UMichigan)

- The UMichigan ILC group (Haijun Yang, Sven Nyberg, Keith Riles) developed an FSI laser alignment system that is *extremely well-suited* to a support structure with potential vibrations and motivation to determine position in real time.



Photodetector

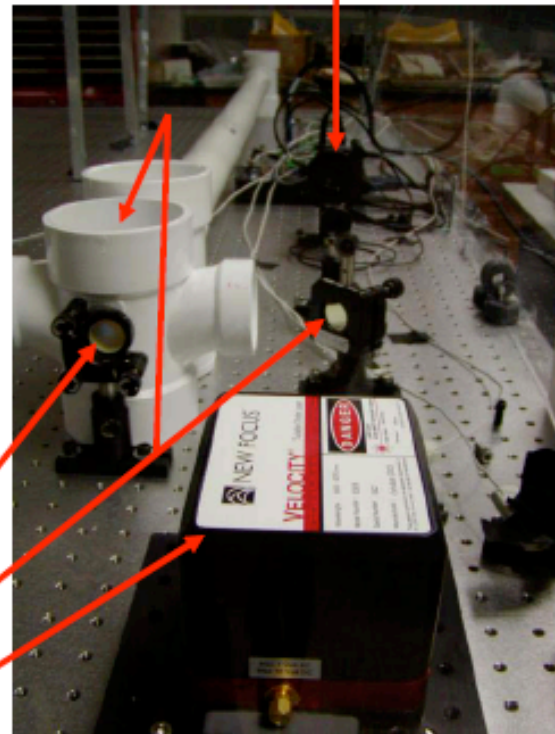
Retroreflector

Mirror

Beamsplitters

Laser

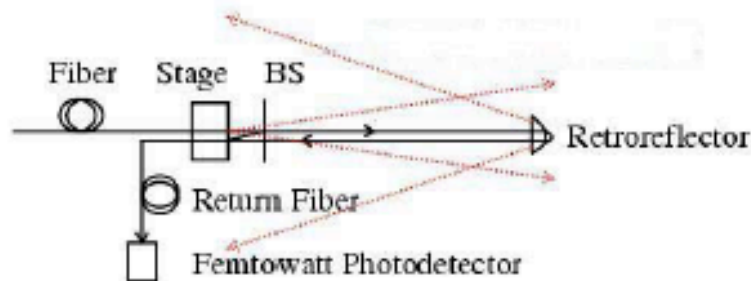
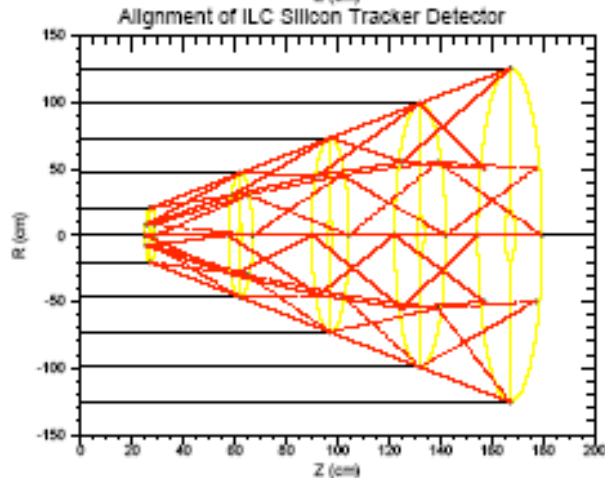
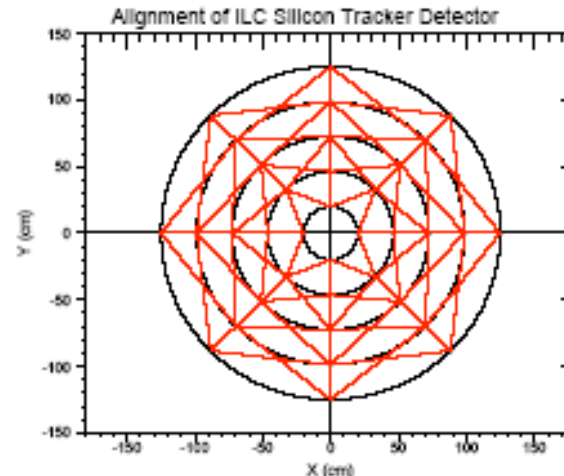
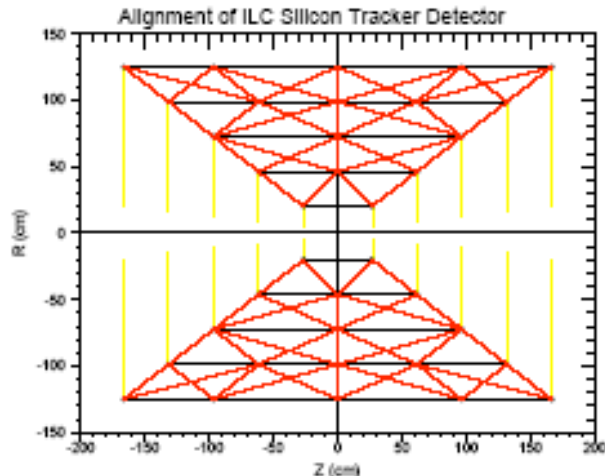
Fabry-Perot Interferometer



- FSI alignment will also be in use for ATLAS SCT (Oxford group + others).
- So there will be additional prior working experience with not-completely-rigid silicon.



# FSI Alignment (UMichigan)



➔ Measurable range

$f_{\text{vib}} = 0.1 \sim 100 \text{ Hz}$ ,

$\text{amp}_{\text{vib}} = \text{few nm} \sim 0.4 \mu\text{m}$

752 point-to-point distance measurements

\* Measured vibration

$f_{\text{vib}} = 1.025 \pm 0.002 \text{ Hz}$ ,

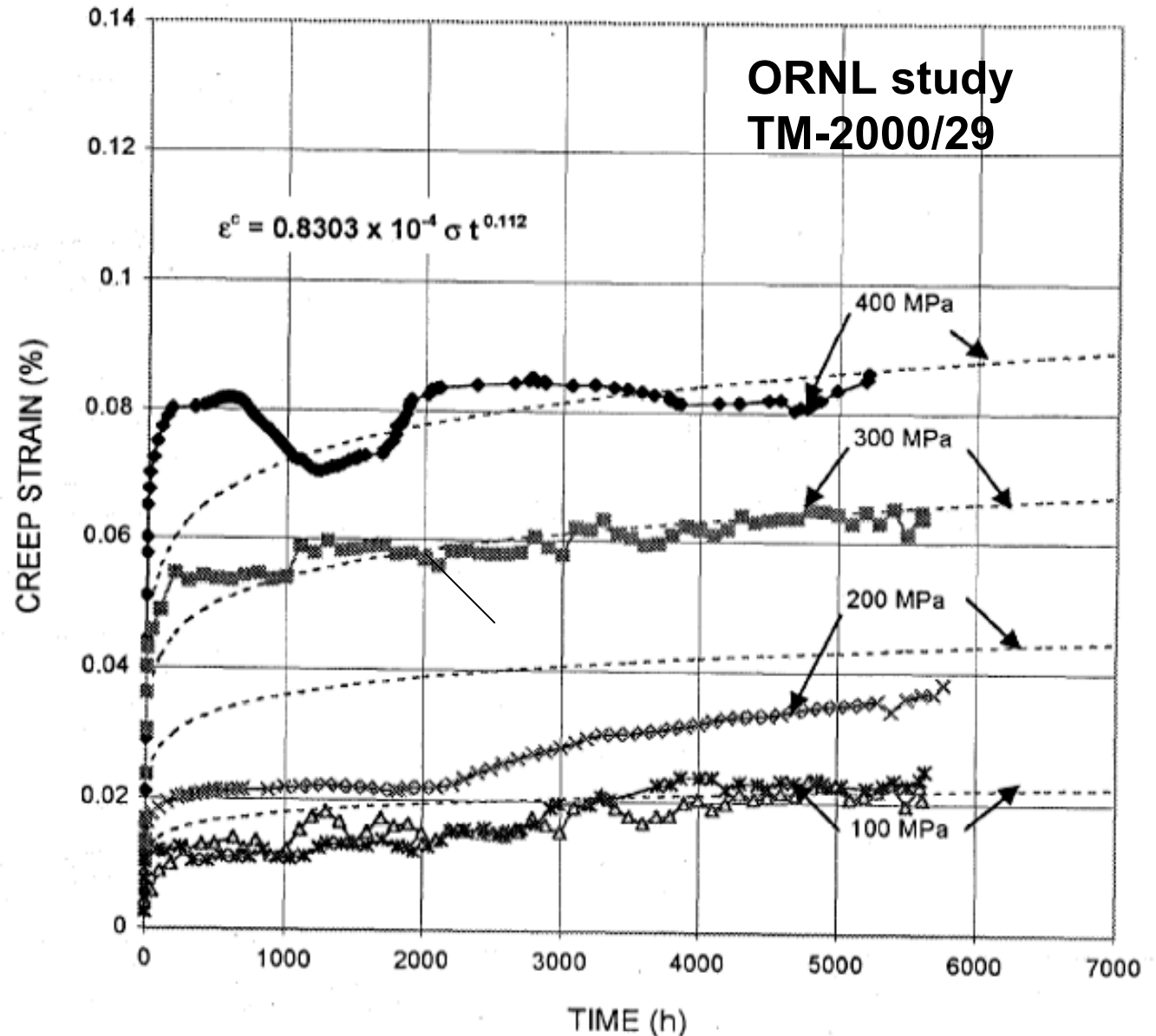
$\text{amp}_{\text{vib}} = 9.3 \pm 0.3 \text{ nanometers}$

!!!

- Using the UMich FSI technology under development, the vibrations in a **filament-based structure** can be **extremely precisely** calibrated *in real time*.

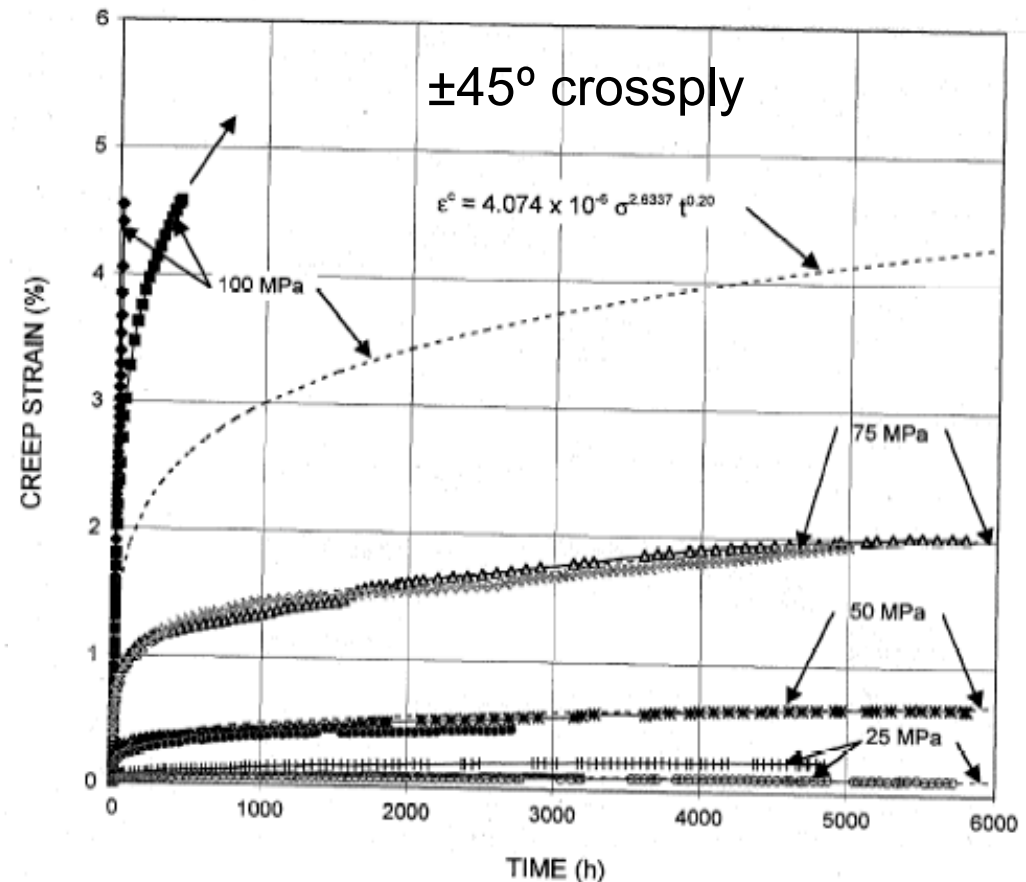
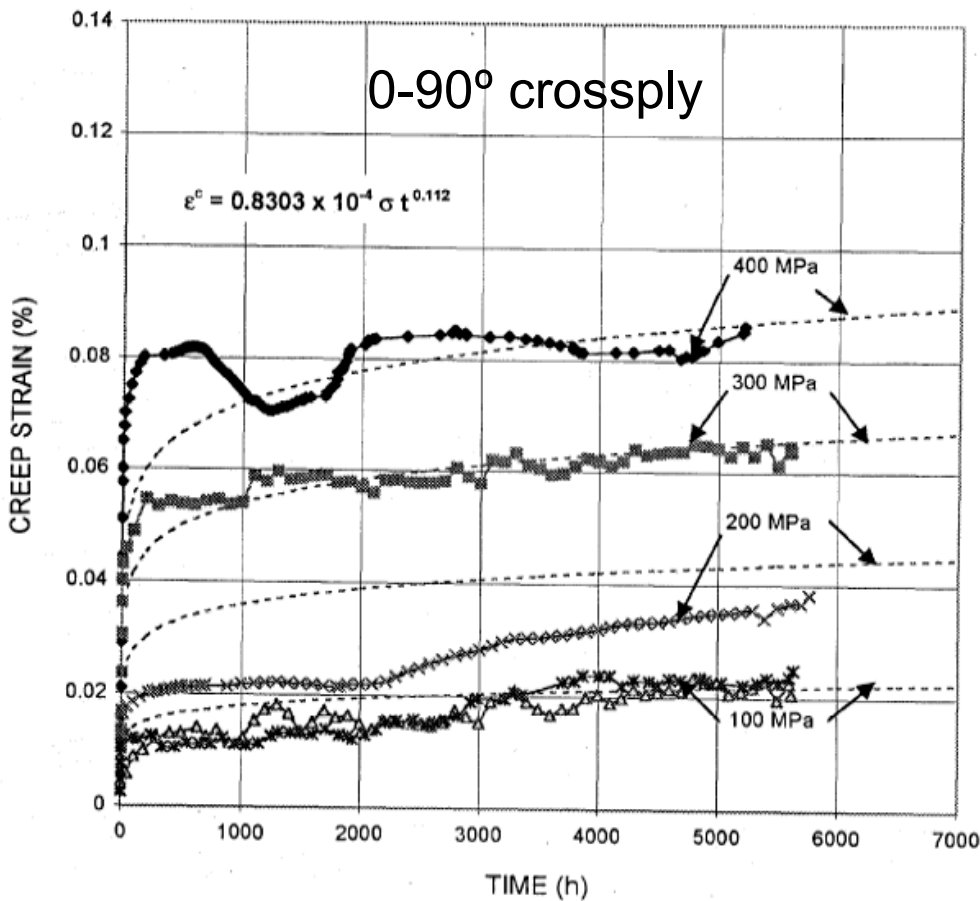
# Filament Creep

- Yield strength = 691 MPa *is not limiting factor.*
- One is more strongly limited by **creep of fibers** over time.
- ORNL reference study of C.F. creep and other properties provides resource.
- C.F. has relatively low creep, nevertheless to assure insignificant creep, we must keep below **~10 MPa**.



# Filament Creep

- But one must be sure to **buy the correct fiber orientation** in C.F. matrix (0-90° crossply)!!
- Otherwise creep strain can rise by factor of ~400 !!!!! (±45° crossply).
- But by keeping tension below measurable strain levels (& *real-time alignment*), creep becomes not a major issue.



# Conclusions

- For low  $p_T$  tracks at SuperB, minimizing material will be critical for high acceptance and efficiency (as well as good momentum resolution).
- Replacing a support frame with filaments would eliminate the vast majority of the inactive material in layer 0.
- **Clearly needs a lot of work: full simulation, FEA study, test setup (!!)**
- Note that this is potentially useful for ILC silicon detectors as well, so deserves further study IMO...

